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Appln. No. 09/681,891

Attorney Docket No. 13378-138

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions and listings of claims in the application.

LISTING OF CLAIMS

- 1-13. (canceled)
- 14. (currently amended) A method of manufacturing a thick film heater comprising a heating element applied directly to a surface of a target object, the method comprising the steps of:

applying the heating element, comprising a thick film resistive circuit, directly to the surface of the target object, wherein the thick film resistive circuit is made of a polymer-based ink;

thermally curing the heating element at a temperature in excess of 150 °C for a first period of time in excess of thirty minutes in a standard curing cycle; and sealing the heating element with a dielectric layer; and

thermally post-curing the heating element and the dielectric layer for second a period of time in a post-curing cycle, the second period of time being longer than the first period of time.

- 15. (canceled)
- 16. (currently amended) The method of claim 14 further comprising the step of preparing the surface of the target object with a lower dielectric layer, and wherein



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the heating element in said applying layer step is applied over the lower dielectric layer.

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- 17. (currently amended) The method of claim 14 wherein said curing step <u>in</u> said standard curing cycle occurs at a temperature of 200 °C or greater.
- 18. (currently amended) The method of claim 14 wherein said <u>first period of time curing step</u> occurs for a period of two hours or longer.
- 19. (original) The method of claim 14 wherein the heating element is designed to operate at greater than 15 W/cm².
 - 20. (original) The method of claim 14 wherein the target object is non-ferrous.
 - 21. (original) The method of claim 20 wherein the target object is aluminum.
 - 22. (original) The method of claim 19 wherein the target object is copper.
 - 23. (original) The method of claim 20 wherein the target object is ceramic.
- 24. (currently amended) The method of claim [[13]] 14 wherein the target object [[is]] comprises high-expansion steel.



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- 25. (currently amended) The method of claim [[13]] 14 wherein the polymer base polymer-based ink of the thick film resistive circuit [[is]] comprises an epoxy.
- 26. (original) The method of claim 24 wherein the polymer-based ink contains silver particles.
 - 27. (new) A thick film heater comprising:
 - a target object to be heated;
- a heating element comprising a polymer-based electrically thick film resistive circuit, the heating element being applied to a surface of the target object, the heating element being thermally cured for a first period of time in a standard curing cycle; and
- a dielectric layer applied over the heating element, the heating element and the dielectric layer being thermally cured for a second period of time in a post-curing cycle, the second period of time being longer than the first period of time.
- 28. (New) The thick film heater of claim 27, wherein the first period of time is at least thirty minutes and the second period of time exceeds sixty minutes.
- 29. (New) The thick film heater of claim 27, wherein the heating element is cured in the standard curing cycle at a temperature of at least 150 °C, and wherein the heating element and the dielectric layer are cured in the post-curing cycle at a temperature of at least 200 °C.



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- 30. (New) The thick film heater of claim 29, wherein the second period of time is at least two and a half hours.
- 31. (New) The thick film heater of claim 30, wherein the second period of time is at least four hours.
- 32. (New) The thick film heater of claim 28, wherein the heating element is cured in the standard curing cycle at a temperature of at least 150 °C, the heating element and the dielectric layer are cured in the post-curing cycle at a temperature of at least 150 °C, and the second period of time is at least three hours.
- 33. (New) The thick film heater of claim 29, wherein the heating element and the dielectric layer are cured in the post-curing cycle at a temperature of at least 225 °C, and the second period of time is at least two hours.
- 34. (New) The thick film heater of claim 27, wherein the heating element is capable of heat flux at least as great as 200 Watts per square inch.
- 35. (New) The thick film heater of claim 27, wherein the target object is non-ferrous.
- 36. (New) The thick film heater of claim 35, wherein the target object is comprised of a material selected from the group consisting of: aluminum, copper, and ceramic.



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37. (New) The thick film heater of claim 27, wherein the target object comprises high-expansion steel.

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- 38. (New) The thick film heater of claim 27, wherein the heating element further comprises a base dielectric layer disposed between the target object and the electrically resistive circuit.
- 39. (New) The thick film heater of claim 38, wherein the base dielectric layer consists of a metal oxide selected from the group consisting of TiO_2 , SiO_2 , and Al_2O_3 .
- 40. (New) The thick film heater of claim 14, wherein the curing step occurs at a temperature of at least 150 °C, and the first time period is at least thirty minutes.
- 41. (New) The method of claim 40, wherein the post-curing step occurs at a temperature of at least 200 °C.
- 42. (New) The method of claim 41, wherein the second period of time exceeds sixty minutes.
- 43. (New) The method of claim 41, wherein the second period of time is at least two and a half hours.
- 44. (New) The method of claim 41, wherein the second period of time is at least four hours.



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- 45. (New) The method of claim 40, wherein the post-curing step occurs at a temperature of at least 150 °C, and the second period of time is at least three hours.
- 46. (New) The method of claim 41, wherein the post-curing step occurs at a temperature of at least 225 °C, and the second period of time is at least two hours.

